

FX602

N-Channel Silicon MOSFET

Ultrahigh-Speed Switching Applications

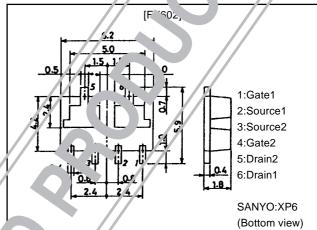
Features

- · Composite type composed of two low ON-resistance N-channel MOSFET chips for ultrahigh-speed switching and low-voltage drive.
- · Facilitates high-density mounting.
- The FX602 is formed with two chips, each being equivalent to the 2SK2152, placed in one package.
- · Matched pair characteristics.

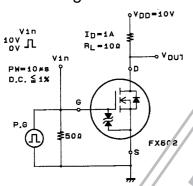
Package Dimensions

unit:mm

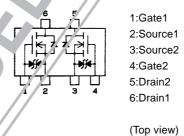
2120



Switching Time Test CIrcuit



Flec rical Connection



Specifications

Absolute Maximum Rating at To = 25°C

P'ara/neter	Sy.nb.ol	Conditions	Ratings	Unit
Drain-to-Source Voltr.ge	VDSS		20	V
Gate-to-Source Voltage	VGSS		±15	V
Drain Curren (CC)	ID		2	Α
Drain Current (Pulse)	I _{DP}	PW≤10µs, duty cycle≤1%	8	А
Allowable Fower Di tion.	PD	Tc=25°C, 1unit	6	W
	PD	Mounted on ceramic board (750mm ² ×0.8mm) 1unit	1.5	W
Total Dissipation	PT	Mounted on ceramic board (750mm ² ×0.8mm)	2	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

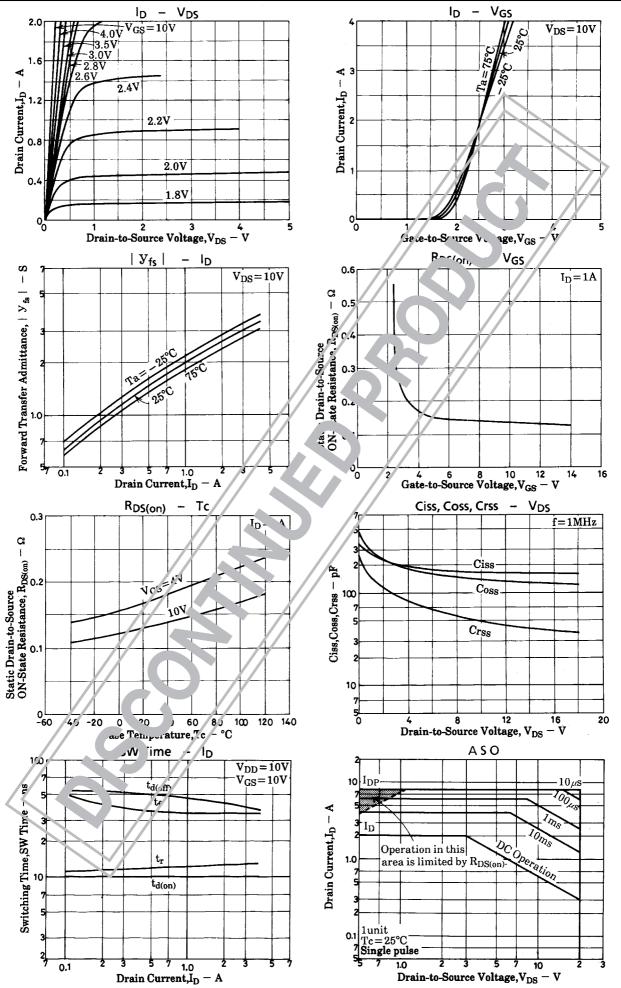
· Marking:602

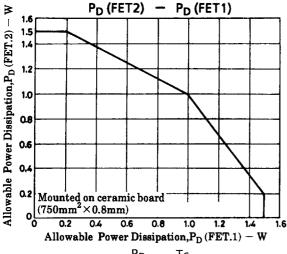
Continued on next page.

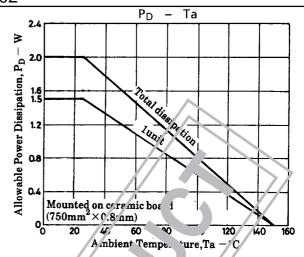
Continued from preceding page.

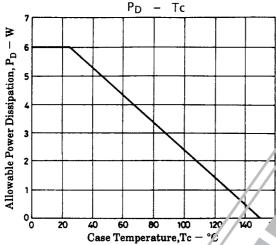
Electrical Characteristics at $Ta = 25^{\circ}C$

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	Offic
D-S Breakdown Voltage	V(BR)DSS	I _D =1mA, V _{GS} =0	20			V
G-S Breakdown Voltage	V _(BR) GSS	I _G =±100μA, V _{DS} =0	±15			V
Zero-Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0			100	μΑ
Gate-to-Source Leakage Current	I _{GSS}	V _{GS} =±12, V _{DS} =0			<u>-</u> 10	μΑ
Cutoff Voltage	VGS(off)	V _{GS} =10V, I _D =1mA	0		2.0	V
Forward Transfer Admittance	Yfs	V _{DS} =10V, I _D =1A	.2	2		S
Static Drain-to-Source ON-State Resistance	R _{DS(on)}	I _D =1A, V _{GS} =10V		100	180	mΩ
	R _{DS(on)}	I_{D} =1A, V_{GS} =4V		170	25′5	mΩ
Input Capacitance	Ciss	V _{DS} =10V, f=1MHz		170		pF
Output Capacitance	Coss	V _{DS} =10V, f=1MHz		145	7	pF
Reverse Transfer Capacitance	Crss	V _{DS} =10V, f=1MHz		50		pF
Turn-ON Delay Time	td(on)	See Specified Test Circuit		10		ns
Rise Time	t _r	See Specified Test Circuit		12		ns
Turn-OFF Delay Time	td(off)	See Specified Test Circuit		50		ns
Fall Time	t _f	See Specified Test Circuit		35		ns
Diode Forward Voltage	V _{SD}	I _S =2A, V _{GS} =0		1.0		V









- No produ 'n esc bed or contained herein are intended for use in surgical implants, life-support systems, aerosp, a equin lent, nuclear power control systems, vehicles, disaster/crime-prevention equipment and the "to the failure of which may directly or indirectly cause injury, death or property loss.
- / vone p chasing any products described or contained herein for an above-mentioned use shall:
 - Acc pt full responsibility and indemnify and defend SANYO ELECTRIC CO., LTD., its affiliates, so sidiaries and distributors and all their officers and employees, jointly and severally, against any and all claims and litigation and all damages, cost and expenses associated with such use:
 - ② Not impose any responsibilty for any fault or negligence which may be cited in any such claim or litigation on SANYO ELECTRIC CO., LTD., its affiliates, subsidiaries and distributors or any of their officers and employees jointly or severally.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. SANYO believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

This catalog provides information as of May, 1998. Specifications and information herein are subject to change without notice.